

## • General Description

The AGM025N13LL combines advanced trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ .

This device is ideal for load switch and battery protection applications.

#### Features

- Advance high cell density Trench technology
- Low R<sub>DS(ON)</sub> to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance
- 100% Avalanche tested
- 100% DVDS tested

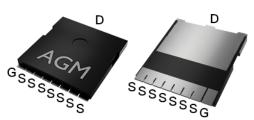
#### Application

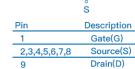
- MB/VGA Vcore
- SMPS 2<sup>nd</sup> Synchronous Rectifier
- POL application
- BLDC Motor driver

## **Product Summary**

BVDSS	RDSON	ID
135V	2.2mΩ	305A

#### **TOLL Pin Configuration**





TOP VIOW BOLLOIN VIOW	Top	View	Bottom	View
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#### **Package Marking and Ordering Information**

De	evice Marking	Device	Device Package	Reel Size	Tape width	Quantity
A	GM025N13LL	AGM025N13LL	TOLL	330mm	25mm	2000

## Table 1. Absolute Maximum Ratings (TA=25℃)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	135	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
ID	Drain Current-Continuous(Tc=25℃) (Note 1)	305	А
	Drain Current-Continuous(Tc=100℃)	215	Α
IDM (pluse)	Drain Current-Pulsed (Note 2)	1220	А
PD	Maximum Power Dissipation(Tc=25℃)	357	W
	Maximum Power Dissipation(Tc=100℃)	143	W
EAS	Avalanche energy (Note 3)	1600	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	$^{\circ}$

## Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
RθJA	Thermal Resistance Junction-ambient (Steady State) <sup>1</sup>		61	°C/W
RθJC	Thermal Resistance Junction-Case <sup>1</sup>		0.35	°C/W



Table 3. Electrical Characteristics (TJ=25℃ unless otherwise noted)

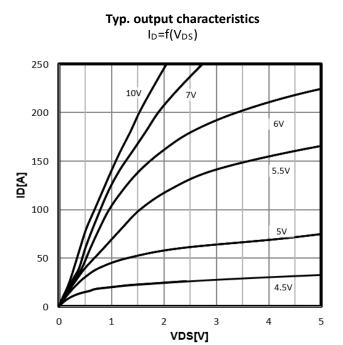
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off Sta	ates					
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=250µA	135			V
IDSS	Zero Gate Voltage Drain Current	VDS=135V,VGS=0V			1	μΑ
IGSS	Gate-Body Leakage Current	VGS=±20V,VDS=0V			±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS,ID=250μA	2.0		4.5	V
gFS	Forward Transconductance	VDS=5V,ID=10A		32		S
RDS(on)	Drain-Source On-State Resistance	VGS=10V, ID=20A		2.2	3.5	mΩ
Dynamic (	Characteristics					
Ciss	Input Capacitance	VDS=40V,VGS=0V		8417		pF
Coss	Output Capacitance	F=1MHZ		3557		pF
Crss	Reverse Transfer Capacitance			360		pF
Rg	Gate resistance	VGS=0V, VDS=0V,f=1.0MHz		0.9		Ω
Switching	Times					
td(on)	Turn-on Delay Time			1.0		nS
tr	Turn-on Rise Time			33		nS
td(off)	Turn-Off Delay Time	VGS=10V,VDS=70V ID=50A,RGEN=4.5Ω		95		nS
tf	Turn-Off Fall Time	ID-30A, NGEN-4.312		75		nS
Qg	Total Gate Charge			1387		nC
Qgs	Gate-Source Charge	VGS=10V, VDS=70V, ID=50A		34		nC
Qgd	Gate-Drain Charge	15 00/1		32		nC
Source-Dr	rain Diode Characteristics					
ISD	Source-Drain Current(Body Diode)				305	А
VSD	Forward on Voltage	VGS=0V,IS=15A			1.2	V
trr	Reverse Recovery Time	IF=15A , dI/dt=100A/μs ,		130		ns
Qrr	Reverse Recovery Charge	TJ=25℃		500		nc

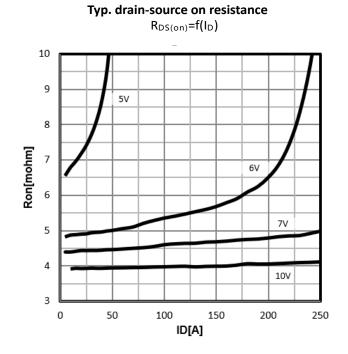
Notes 1. The maximum current rating is package limited.

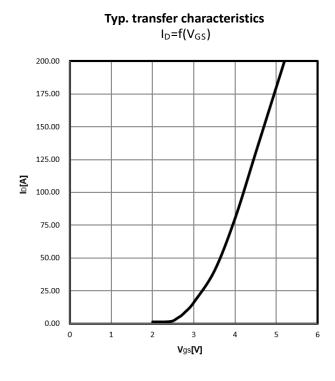
Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

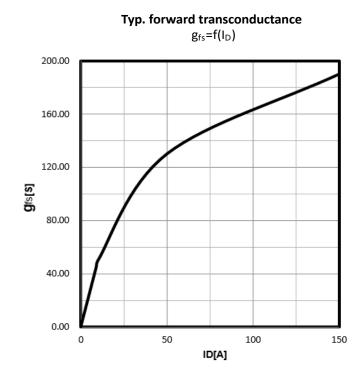
Notes 3.EAS condition: TJ=25  $^{\circ}\text{C}$  ,VDD=50V,Vgs=10V, ID=80A,L=0.5mH,RG=25ohm







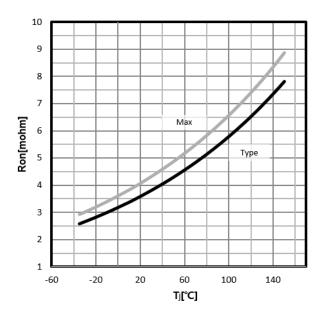




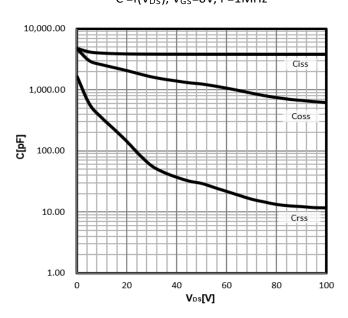


Drain-source on-state resistance

 $R_{DS(on)}$ =f(T  $_j$  );  $I_D$ =80A;  $V_{GS}$ =10V

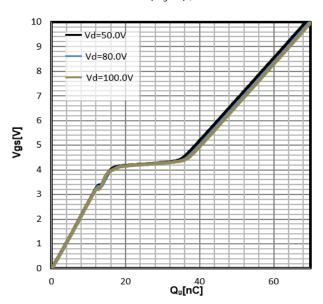


Typ. capacitances  $C = f(V_{DS}); V_{GS} = 0V; f = 1MHz$ 



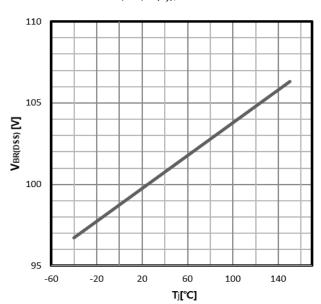
Typ. gate charge

 $V_{GS}$ = $f(Q_{gate})$ ;  $I_D$ =20A

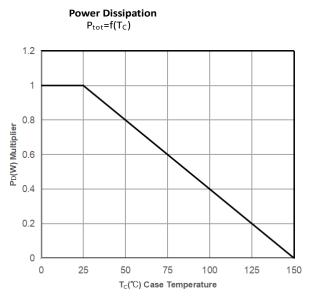


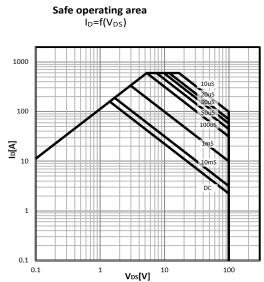
## Drain-source breakdown voltage

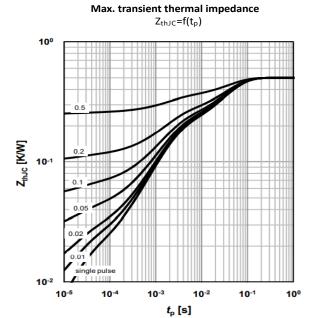
 $V_{BR(DSS)}=f(T_j); I_D=250uA$ 





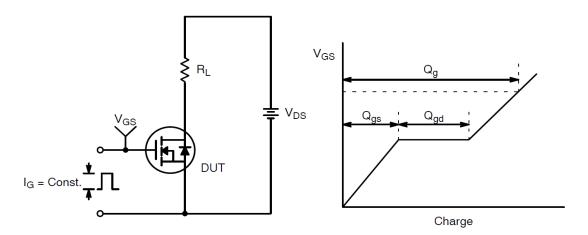




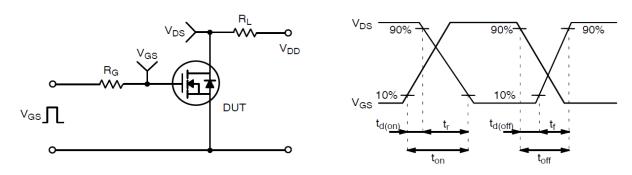




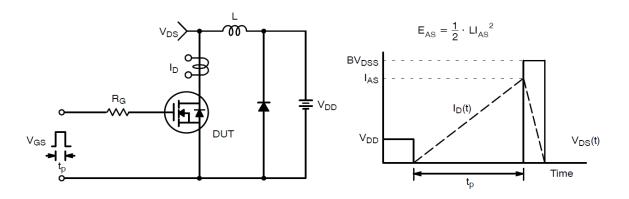
## **Test Circuit and Waveform:**



**Gate Charge Test Circuit & Waveform** 



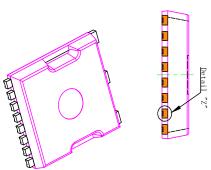
**Resistive Switching Test Circuit & Waveforms** 

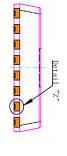


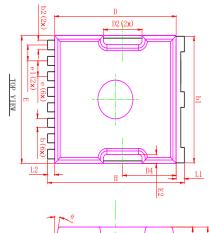
**Unclamped Inductive Switching Test Circuit & Waveforms** 

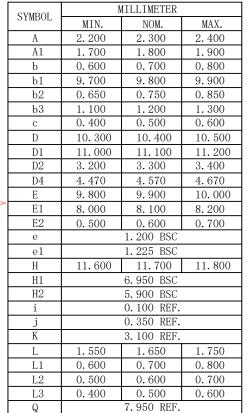


# **TOLL Package**

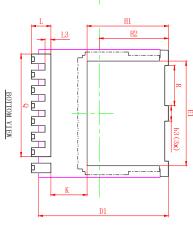




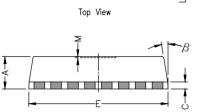


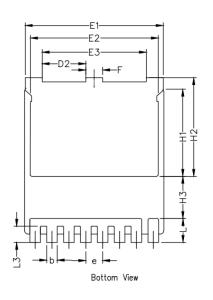






	-	-E	R	R0.250 0.150.250 0.3
	+	A. Solo	,	<u>†</u>
, ,,			<del>   </del> _	¥ <b>∓</b> ≥
	T	op View		





Q

R

3.000

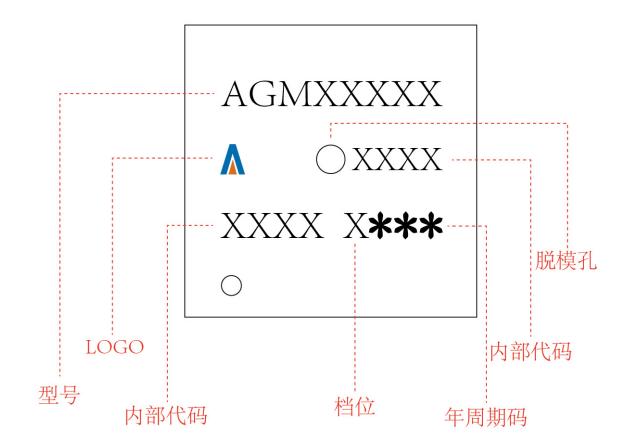
3. 100

3.200

C L . I .	Millimeters			
Symbols	MIN.	NOM.	MAX.	
Α	2.20	2.30	2.40	
b	0.65	0.75	0.85	
С	0	.508 R	EF	
D	10.25	10.40	10.55	
D1	2.85	3.00	3.15	
D2	2.95	3.10	3.25	
D3	0	.75 RE	F	
Ε	9.75	9.90	10.05	
E1	9.65	9.80	9.95	
E2	8.95	9.10	9.25	
E3	7.25	7.40	7.55	
е	1.20 BSC			
F	1.05	1.20	1.35	
Н	11.55	11.70	11.85	
H1	6.03	6.18	6.33	
H2	6.85	7.00	7.15	
Н3	,	3.00 BS	SC	
L	1.55	1.70	1.85	
L1	0.55	0.70	0.85	
L2	0.45	0.60	0.75	
L3	1.00	1.15	1.30	
М	0.08 REF			
β	8.	10°	12 <b>°</b>	
K	4.25	4.40	4.55	



TOLL Marking Instructions:





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